ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute					Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
Supplier Inform	ation														
Company name*			Company unique ID			τ	Unique ID Authority					Response Date*			
nsemi												2025-08-28			
Contact Name			Title - Contact			1	Phone - Contact*				Email - Contact*				
Product-Env-Stewa	rds		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			1	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
Requester	r Item Number			per Mfr Item Name			Effective Date	e Vers	ion	Manufacturing Site		V	eight*	UOM	Unit Type
				Integrated Driver	d Driver and MOSFET		2025-08-28 PI		РНА		10	01.13	mg	Each	
Ianufacturing l	Proccess Informatio	n													
Terminal Plating / Grid Array Material			Ferminal Base Alloy J-STD-020 M		SL Rating	Peak Process Body Temperate		ure Max Time at Peak Tempera		Temperatu	re Numb	per of Reflow Cyc	les		
Matte Tin	(Sn) - annealed	C	U Alloy		3		260		C	30		second	s 3		
omments															
TTENTION: MSL	3 Rated item requires B	ake and Di	ry Pack (after	r electrical test)											
or more informatio	on regarding material co	mposition p	olease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominal contains a RoHS restricted substance inexcess encompass all such components. Supplier certi as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided by certification in this paragraph. If the Company	ted biphenyls and/or polybrominated diphenyls of an applicable quantity limit, please indication in the graph of an applicable quantity limit, please indications. Supplier acknowledges that Company will we relied on information provided by others in a minimum and the Supplier agrees that, at a minimum and the Supplier enter into a written agreem source of the Supplier's liability and the Company of the Supplier's liability and the Supplier's liability and the Supplier's liability and the Company of the Supplier's liability and the Supplier's liabi	J 2011/65/EU and implemented by the laws of the Eyl ethers (each a "RoHS restricted substance") in exate below which, if any, RoHS exemption you belie les in this form using appropriate methods to ensure rely on this certification in determining the complian completing this form, and that Supplier may not ha, its suppliers have provided certifications regarding tent with respect to the identified part, the terms and impany's remedies for issues that arise regarding info cable to such part shall apply.	cess of the applicable quantity limit identified ab we may apply. If the part is an assembly with low its accuracy and that such information is true an- unce of its products with European Union member ave independently verified such information. Ho their contributions to the part, and those certifications conditions of that agreement, including any warr	ove. If a homogeneous material within the part ver level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		'Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-6_								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.02	mg	Supplier	Silicon (Si)	7440-21-3		3.02	mg
Die Attach Solder	5.35	mg	Supplier	Silver (Ag)	7440-22-4		0.1338	mg
			A	Lead (Pb)	7439-92-1	7a	4.9488	mg
			Supplier	Tin (Sn)	7440-31-5		0.2675	mg
Lead Frame	59.54	mg	Supplier	Silver (Ag)	7440-22-4		0.9824	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0714	mg
			Supplier	Iron (Fe)	7439-89-6		1.3992	mg
			Supplier	Copper (Cu)	7440-50-8		57.0691	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0179	mg
Mold Compound-Black	31.34	mg	Supplier	Epoxy resins	129915-35-1		1.567	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.567	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1254	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.7208	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		26.639	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.7208	mg
Plating	1.57	mg	Supplier	Tin (Sn)	7440-31-5		1.57	mg
Wire Bond - Au	0.31	mg	Supplier	Gold (Au)	7440-57-5		0.31	mg